
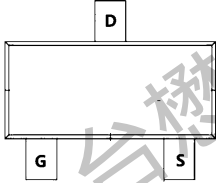
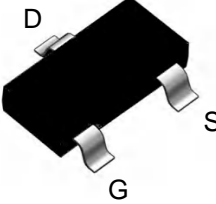
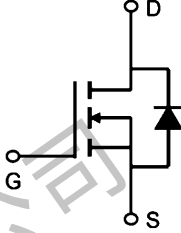


TM03N02MI

N-Channel Enhancement Mosfet

<p>General Description</p> <ul style="list-style-type: none"> • Low $R_{DS(ON)}$ • RoHS and Halogen-Free Compliant <p>Applications</p> <ul style="list-style-type: none"> • Load switch • PWM 	<p>General Features</p> <p>$V_{DS} = 20V$ $I_D = 3.2A$ $R_{DS(ON)} = 40 m\Omega (Typ.) @ V_{GS} = 4.5V$</p> <p>100% UIS Tested 100% R_g Tested</p> 
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MI:SOT-23-3L

Marking: A2SHB

Absolute Maximum Ratings ($T_C = 25^\circ C$ unless otherwise noted)

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	20	V
V_{GS}	Gate-Source Voltage	± 12	V
$I_D @ T_A = 25^\circ C$	Continuous Drain Current, $V_{GS} @ 4.5V^1$	3.2	A
I_{DM}	Pulsed Drain Current ²	12	A
$P_D @ T_A = 25^\circ C$	Total Power Dissipation ³	0.9	mW
T_{STG}	Storage Temperature Range	-55 to 175	$^\circ C$
T_J	Operating Junction Temperature Range	-55 to 175	$^\circ C$

Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-ambient ¹	---	139	$^\circ C/W$
$R_{\theta JC}$	Thermal Resistance Junction-Case ¹	---	---	$^\circ C/W$

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N-Channel Enhancement Mosfet

Electrical Characteristics (T_J=25°C unless otherwise specified)

Characteristic	Symbol	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage (I _D =250uA, V _{GS} =0V)	BV _{DSS}	20	—	—	V
Gate Threshold Voltage(I _D =250uA, V _{GS} = V _{DS})	V _{GS(th)}	0.5	0.7	0.9	V
Zero Gate Voltage Drain Current (V _{GS} =0V, V _{DS} = 20V)	I _{DSS}	—	—	1	uA
Gate Body Leakage (V _{GS} =±10V, V _{DS} =0V)	I _{GSS}	—	—	±100	nA
Static Drain-Source On-State Resistance (I _D =3.5A, V _{GS} =4.5V) (I _D =2A, V _{GS} =2.5V)	R _{DS(ON)}	—	40 55	52 80	mΩ
Diode Forward Voltage Drop (I _{SD} =3A, V _{GS} =0V)	V _{SD}	—	—	1.2	V
Input Capacitance (V _{GS} =0V, V _{DS} =10V, f=1MHz)	C _{ISS}	—	220	—	pF
Common Source Output Capacitance (V _{GS} =0V, V _{DS} =10V, f=1MHz)	C _{OSS}	—	34	—	pF
Reverse Transfer Capacitance (V _{GS} =0V, V _{DS} =10V, f=1MHz)	C _{RSS}	—	26	—	pF
Total Gate Charge (V _{DS} =10V, I _D =3A, V _{GS} =4.5V)	Q _g	—	3.6	—	nC
Gate Source Charge (V _{DS} =10V, I _D =3A, V _{GS} =4.5V)	Q _{gs}	—	0.9	—	nC
Gate Drain Charge (V _{DS} =10V, I _D =3A, V _{GS} =4.5V)	Q _{gd}	—	0.8	—	nC
Turn-ON Delay Time (V _{DS} =10V I _D =3A, R _{GEN} =3 Ω, V _{GS} =4.5V)	t _{d(on)}	—	8	—	ns
Turn-ON Rise Time (V _{DS} =10V I _D =3A, R _{GEN} =3 Ω, V _{GS} =4.5V)	t _r	—	58	—	ns
Turn-OFF Delay Time (V _{DS} =10V I _D =3A, R _{GEN} =3 Ω, V _{GS} =4.5V)	t _{d(off)}	—	15	—	ns
Turn-OFF Fall Time (V _{DS} =10V I _D =3A, R _{GEN} =3 Ω, V _{GS} =4.5V)	t _f	—	53	—	ns

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N-Channel Enhancement Mosfet

Typical Characteristic Curve

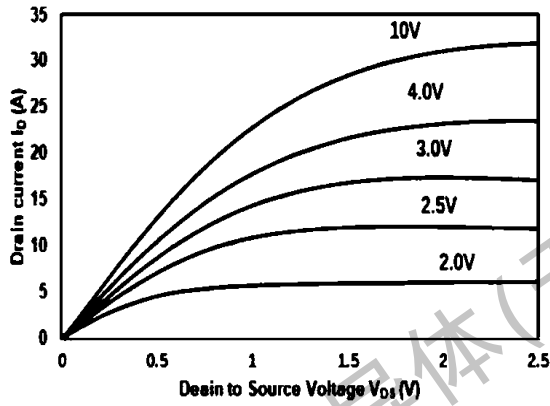


Figure 1: Output Characteristics

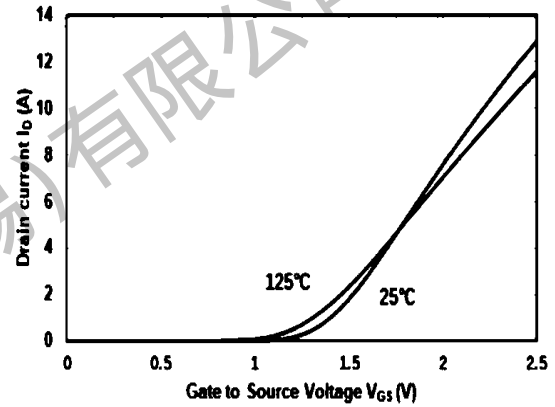


Figure 2: Transfer Characteristics

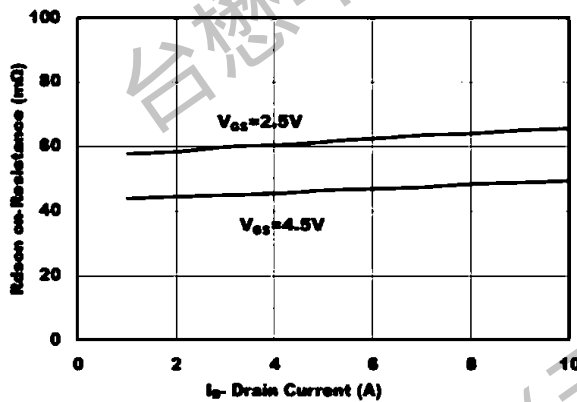


Figure 3: On-Resistance vs. Drain Current

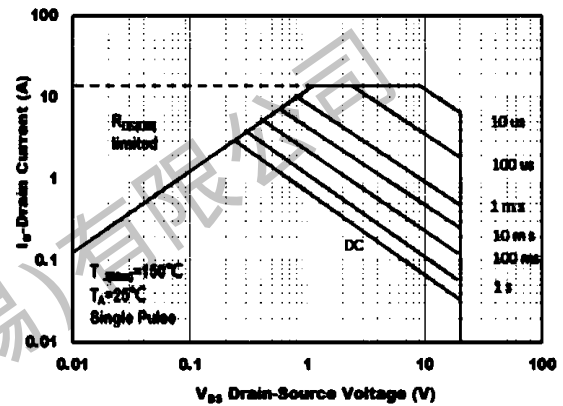


Figure 4: Safe Operating Area

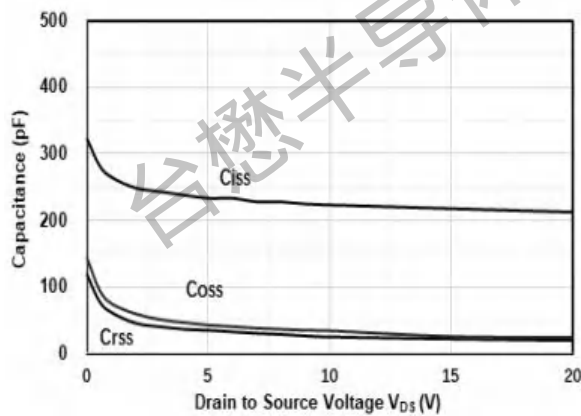


Figure 5: Capacitance Characteristics

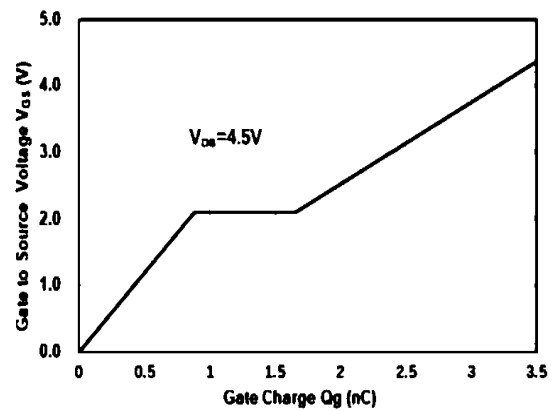
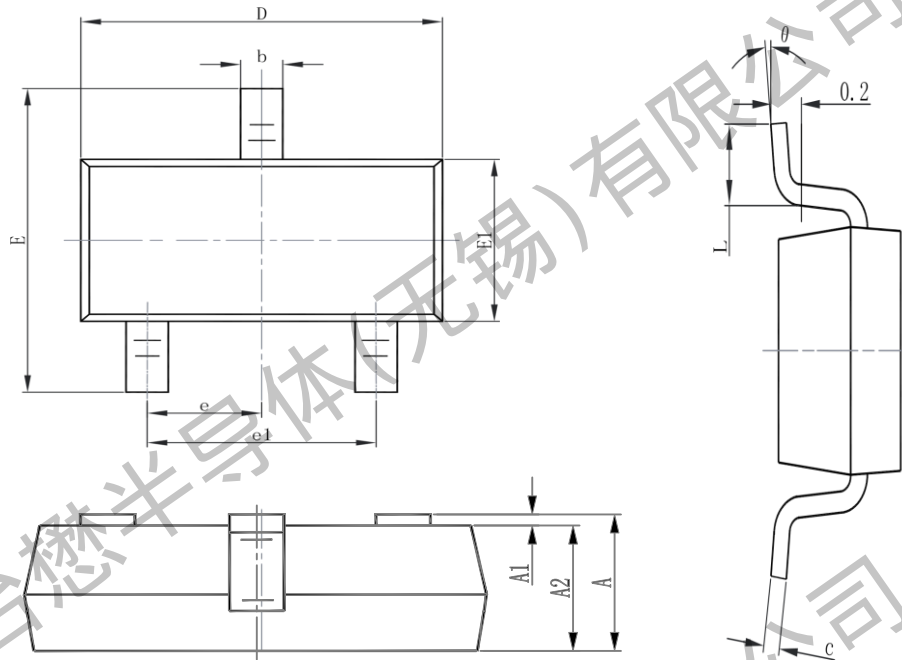


Figure 6: Gate-Charge Characteristics

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Package Mechanical Data:SOT-23-3L



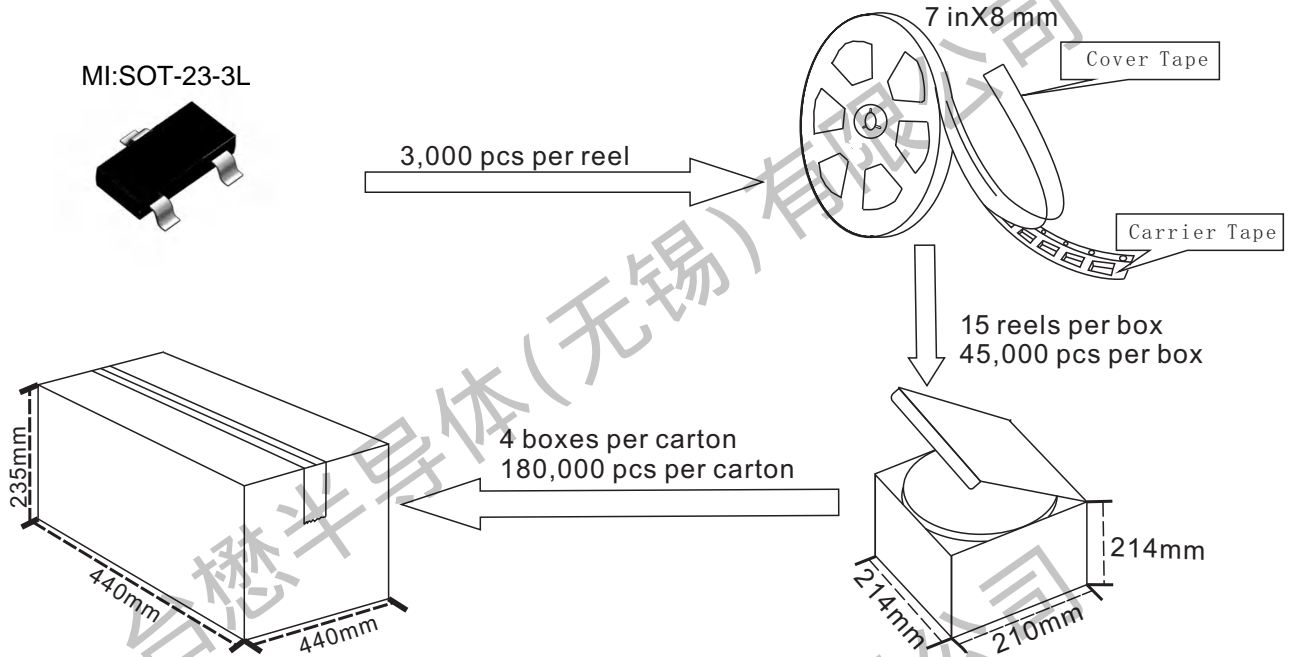
Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	1.050	1.250	0.041	0.049
A1	0.000	0.100	0.000	0.004
A2	1.050	1.150	0.041	0.045
b	0.300	0.500	0.012	0.020
c	0.100	0.200	0.004	0.008
D	2.820	3.020	0.111	0.119
E1	1.500	1.700	0.059	0.067
E	2.650	2.950	0.104	0.116
e	0.950(BSC)		0.037(BSC)	
e1	1.800	2.000	0.071	0.079
L	0.300	0.600	0.012	0.024
theta	0°	8°	0°	8°

TM03N02MI

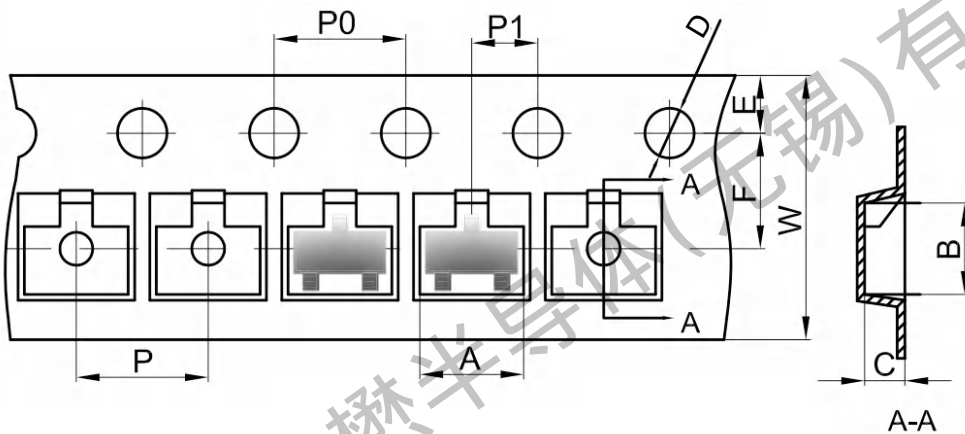
N-Channel Enhancement Mosfet

SOT-23-3L Packing

1. The method of packaging and dimension are shown as below figure. (Dimension in mm)



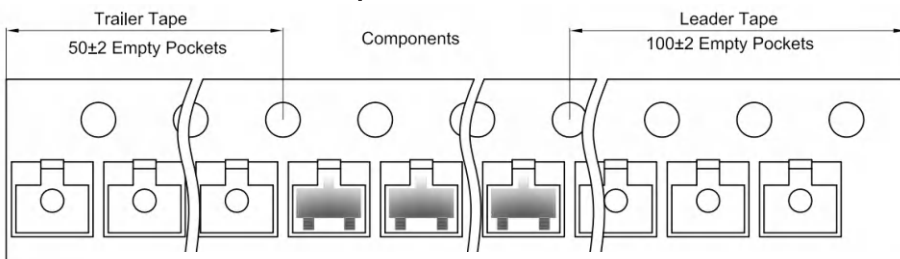
SOT-23-3L Embossed Carrier Tape



Dimensions are in millimeter

Pkg type	A	B	C	D	E	F	P0	P	P1	W
SOT-23-3L	3.15	2.77	1.22	Ø1.50	1.75	3.50	4.00	4.00	2.00	8.00

SOT-23-3L Tape Leader and Trailer



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Revision history:

Date	Rev	Description	Page
2023.05.06	23.05	Original	